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Polymer PTC Devices

Surface mount fuses

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LP-NSM050

Features

- □ Very small size of 1206
- □ Fast tripping resettable circuit protection
- Agency recognition: UL、CSA、TUV Mus III

Product Dimensions (mm)

Part number -	Α	В	С	D	E
	Max	Max	Max	Max	Min.
LP-NSM050	3.50	1.80	0.85	0.60	0.20



Electrical Characteristics

Dant month an	Ι _Η	Ι _Τ	V _{max}	I _{max}	T _{trip})	Pd _{typ}	R _{min}	R _{1max}
Part number	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-NSM050	0.50	1.00	6	40	8.0	0.10	0.60	0.15	0.70

 I_{H} =Hold current: maximum current at which the device will not trip at 25 still air.

I_T=Trip current: minimum current at which the device will always trip at 25 still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

 $I_{\text{max}} = Maximum$ fault current device can withstand without damage at rated voltage.

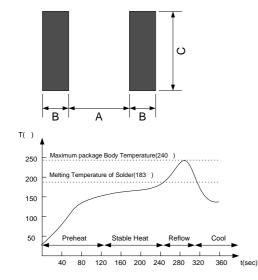
 T_{trip} =Maximum time to trip(s) at assigned current.

Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25 prior to tripping.

R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	Α	В	С
Fart number -	(mm)	(mm)	(mm)
LP-NSM035	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 4000pcs per reel.

